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IN THE U.S. PATENT AND TRADEMARK OFFICE

April 4, 2011

Applicants: Atsushi YABE et al

For: ELECTROLESS COPPER PLATING SOLUTION

Serial No.: 10/576 231 Group: 1792

Confirmation No.: 7188

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Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

STATUS REQUEST

Sir:

An RCE was filed in the above application on April 5, 2010. To date, the undersigned attorney of record has not received an Office Action. Please advise the undersigned attorney of record of the status concerning the above-referenced application as soon as possible.

Respectfully submitted,

Terryence F. Chapman

TFC/smd

FLYNN, THIEL, BOUTELL Terryence F. Chapman Reg. No. 32 549
& TANIS, P.C. Mark L. Maki Reg. No. 36 589
2026 Rambling Road Liane L. Churney Reg. No. 40 694
Kalamazoo, MI 49008-1631 Brian R. Tumm Reg. No. 36 328
Phone: (269) 381-1156 Heon Jekal Reg. No. 64 219
Fax: (269) 381-5465 Eugene J. Rath III Reg. No. 42 094
Dale H. Thiel Reg. No. 24 323
David G. Boutell Reg. No. 25 072
Sidney B. Williams, Jr. Reg. No. 24 949

Encl: Postal Card

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on April 4, 2011.

Terryence F. Chapman